

Absolute Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V_{CBO}	75	V
Collector-Emitter Voltage	V_{CEO}	40	V
Emitter-Base Voltage	V_{EBO}	6	V
Collector Current	Ic	600	mA

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 5)	P_{D}	200	mW
Thermal Resistance, Junction to Ambient (Note 5)	$R_{ heta JA}$	625	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

ESD Ratings (Note 6)

Characteristic	Symbol	Value	Unit	JEDEC Class
Electrostatic Discharge - Human Body Model	ESD HBM	4,000	V	3A
Electrostatic Discharge - Machine Model	ESD MM	400	V	С

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 7)	OFF CHARACTERISTICS (Note 7)				
Collector-Base Breakdown Voltage	BV _{CBO}	75	_	V	$I_C = 10\mu A, I_E = 0$
Collector-Emitter Breakdown Voltage	BV _{CEO}	40	_	V	$I_C = 10 \text{mA}, I_B = 0$
Emitter-Base Breakdown Voltage	BV _{EBO}	6.0	_	V	$I_E = 10\mu A, I_C = 0$
Collector Cut-Off Current	I _{CBO}	_	10	nA µA	V _{CB} = 60V, I _E = 0 V _{CB} = 60V, I _E = 0, T _A = +150°C
Collector Cut-Off Current	I _{CEX}	_	10	nA	$V_{CE} = 60V$, $V_{EB(OFF)} = 3V$
Base Cutoff Current	I _{BL}	_	20	nA	$V_{CE} = 60V$, $V_{EB(OFF)} = 3V$
ON CHARACTERISTICS (Note 7)		l.			, 25(0)
DC Current Gain	h _{FE}	35 50 75 100 40 50 35	 300 	_	$\begin{split} &I_{C}=100\mu\text{A},\ V_{CE}=10\text{V}\\ &I_{C}=1.0\text{mA},\ V_{CE}=10\text{V}\\ &I_{C}=10\text{mA},\ V_{CE}=10\text{V}\\ &I_{C}=150\text{mA},\ V_{CE}=10\text{V}\\ &I_{C}=500\text{mA},\ V_{CE}=10\text{V}\\ &I_{C}=10\text{mA},\ V_{CE}=10\text{V},\ T_{A}=-55^{\circ}\text{C}\\ &I_{C}=150\text{mA},\ V_{CE}=1.0\text{V} \end{split}$
Collector-Emitter Saturation Voltage	V _{CE(SAT)}	_	0.3 1.0	V	$I_C = 150$ mA, $I_B = 15$ mA $I_C = 500$ mA, $I_B = 50$ mA
Base-Emitter Saturation Voltage	V _{BE(SAT)}	0.6 —	1.2 2.0	V	$I_C = 150 \text{mA}, I_B = 15 \text{mA}$ $I_C = 500 \text{mA}, I_B = 50 \text{mA}$
SMALL SIGNAL CHARACTERISTICS					
Output Capacitance	C _{obo}	_	8	pF	$V_{CB} = 10V, f = 1.0MHz, I_E = 0$
Input Capacitance	Cibo	_	25	pF	$V_{EB} = 0.5V, f = 1.0MHz, I_{C} = 0$
Current Gain-Bandwidth Product	f⊤	300		MHz	$V_{CE} = 20V$, $I_C = 20mA$, $f = 1.0MHz$
Noise Figure	NF	_	4.0	dB	$V_{CE} = 10V, I_{C} = 100\mu A,$ $R_{S} = 1k\Omega, f = 1.0kHz$
SWITCHING CHARACTERISTICS					
Delay Time	t _d	_	10	ns	$V_{CC} = 30V, I_C = 150mA,$
Rise Time	t _r	_	25	ns	$V_{BE(OFF)} = -0.5V, I_{B1} = 15mA$
Storage Time	ts	_	225	ns	$V_{CC} = 30V, I_C = 150mA,$
Fall Time	t _f	_	60	ns	$I_{B1} = I_{B2} = 15mA$

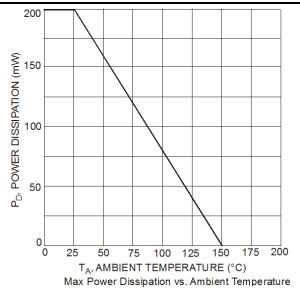
Notes: 5. For a device mounted with the collector lead on minimum recommended pad layout 1oz copper that is on a single-sided 1.6mm FR-4 PCB; device is measured under still air conditions whilst operating in a steady-state.

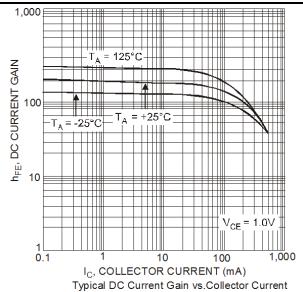
^{6.} Refer to JEDEC specification JESD22-A114 and JESD22-A115.

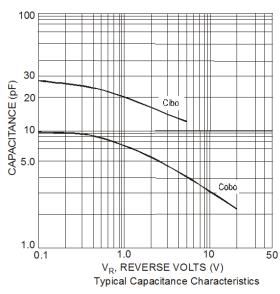
^{7.} Measured under pulsed conditions. Pulse width \leq 300 μ s. Duty cycle \leq 2%.

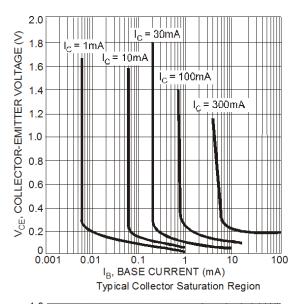


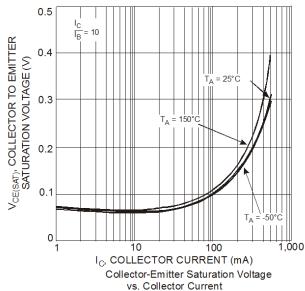
Typical Electrical Characteristics (@TA = +25°C, unless otherwise specified.)

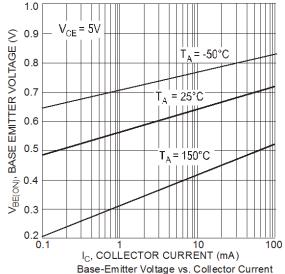






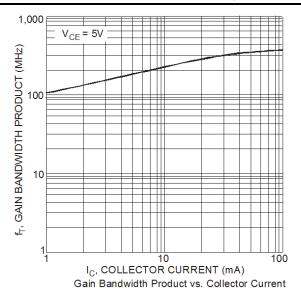








Typical Electrical Characteristics (Cont. @T_A = +25°C, unless otherwise specified.)

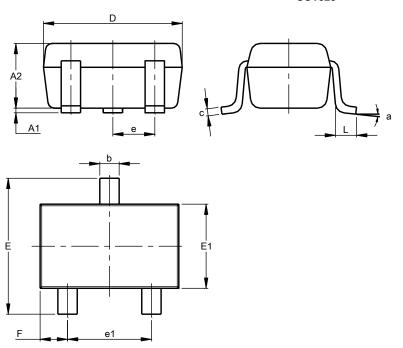




Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

SOT323

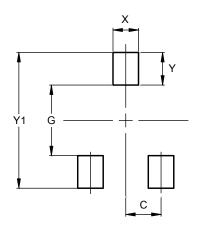


SOT323					
Dim	Min	Max	Тур		
A1	0.00	0.10	0.05		
A2	0.90	1.00	0.95		
b	0.25	0.40	0.30		
С	0.10	0.18	0.11		
D	1.80	2.20	2.15		
E	2.00	2.20	2.10		
E1	1.15	1.35	1.30		
е	0.650 BSC				
e1	1.20	1.40	1.30		
F	0.375	0.475	0.425		
L	0.25	0.40	0.30		
а	0°	8°			
All Dimensions in mm					

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

SOT323



Dimensions	Value (in mm)
С	0.650
G	1.300
Х	0.470
Y	0.600
Y1	2.500



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